

REMARKS

Reconsideration of this application in view of the above amendments and following remarks is respectfully requested. This application has been allowed (Notice of Allowance dated May 18, 2004) and the Issue Fee has already been paid (June 17, 2004). Regrettably, the Office of Patent Publications (PUBS) has now taken the position that many of the drawings of record are not acceptable for a variety of reasons. Because many of the original drawings are no longer available, and because many of the drawings are not necessary to satisfy the requirements of 35 U.S.C. § 112, first paragraph, Applicants have elected to delete the offending drawings and to appropriately amend the specification. Accordingly, Applicants submit this RCE amendment pursuant to 37 CFR § 1.114 and respectfully request that this application be amended in the manner suggested and promptly issued as a U.S. Patent. No new matter has been added.

If any further matter requires attention prior to issuance, the Examiner is respectfully requested to contact the undersigned attorney at (206) 381-3100 to resolve the same. Please charge any underpayment of fees or credit any overpayment to Deposit Account No. 02-0915.

Respectfully submitted,

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Appl. No. 09/858,327
Amendment dated November 10, 2004
Reply to Notice Regarding Drawings dated October 4, 2004

Amendments to the Drawings:

Applicant respectfully submits on separate papers attached hereto amended drawings (i.e., replacement sheets and annotated sheets showing changes) showing the proposed changes in red for approval by the Examiner.

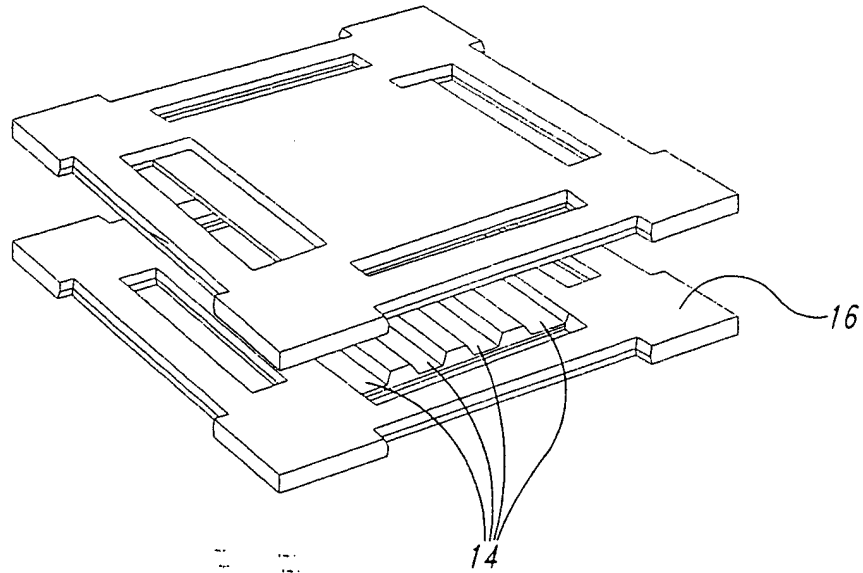
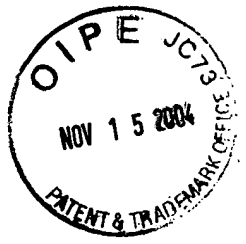


Fig. ~~1~~ 1

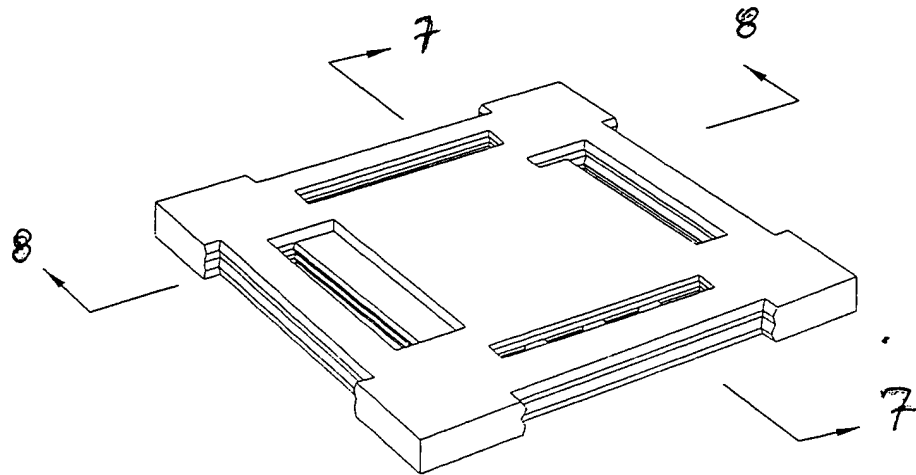


Fig. ~~2~~ 2

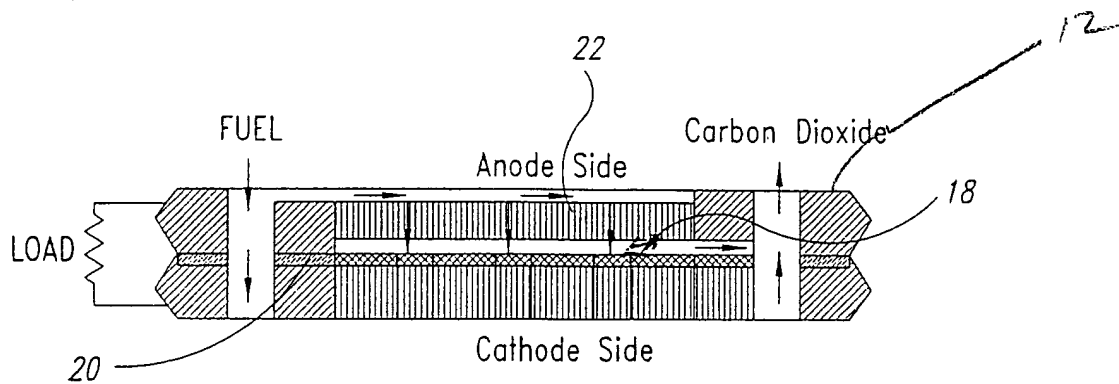
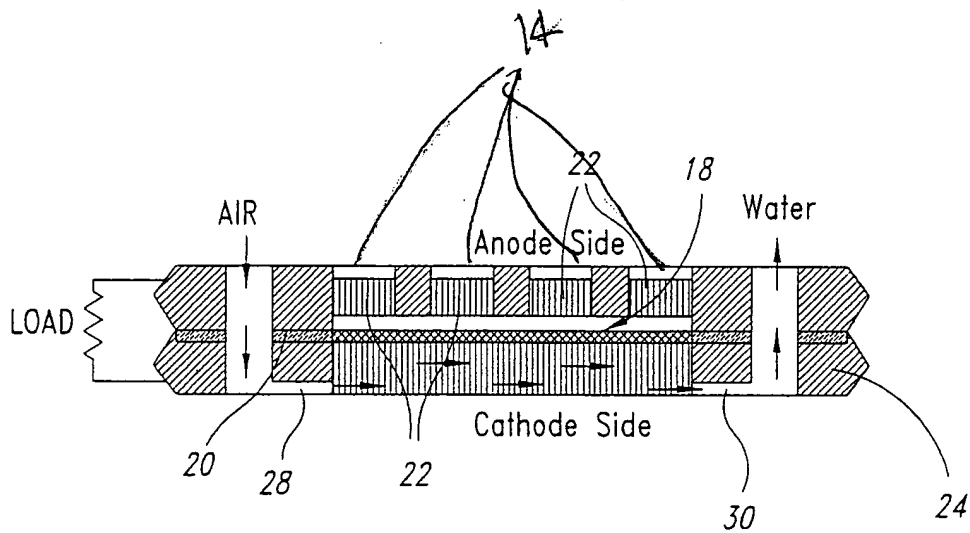


Fig. ~~3~~ 3



- | | | | |
|--|-------------------|--|------------------------|
| | Flow Channel | | Porous Catalyst Region |
| | Silicon Substrate | | Methanol Barrier Layer |
| | | | Wafer Bonding Material |

Fig. ~~4~~ 4

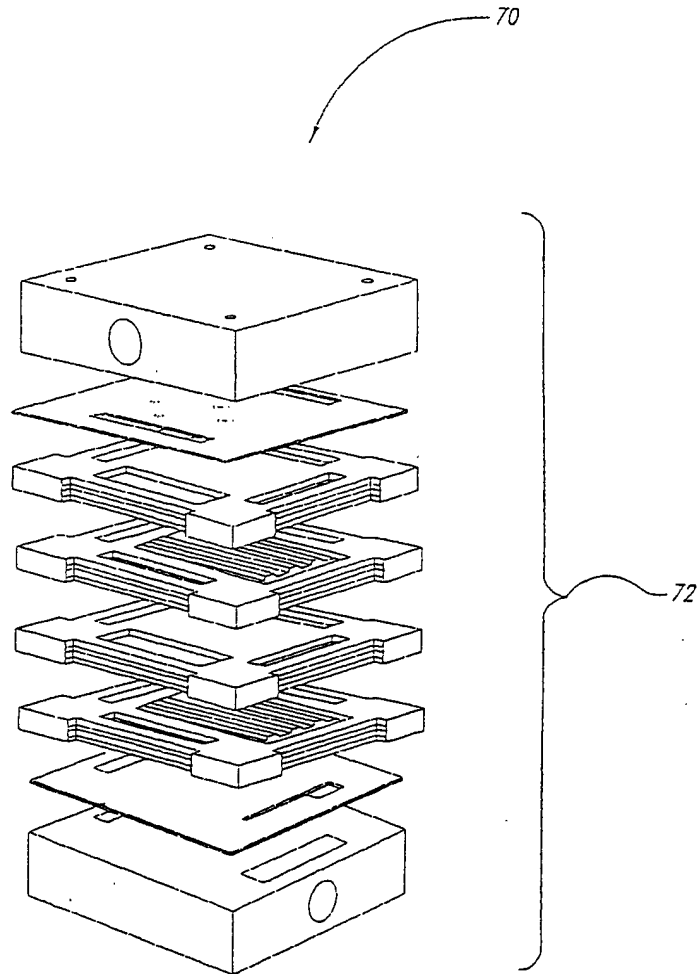
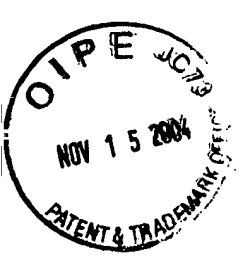


Fig. 5